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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Wei Lee

Group Art Unit: 1765

Serial No.: 09/822,532

Examiner: Charlotte A. Brown

Filed: March 30, 2001

In Response to Office Action

Dated: Oct. 4, 2002

For: Method For Forming Aluminum Bumps By Sputtering
And Chemical Mechanical Polishing

Attorney Docket No.: 67,200-390

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: Jan. 6, 2003


Kathy Dixon

RESPONSE TO OFFICE ACTION

Assistant Commissioner
for Patents
Washington, D.C. 20231

Dear Sir:

In response to an Office Action mailed October 4, 2002, please enter the following amendments and consider the following remarks.